

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2753025

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>SARAD BAHADUR THAPA</td> <td>02/24/2014</td> </tr> <tr> <td>THOMAS SCHROEDER</td> <td>02/24/2014</td> </tr> <tr> <td>LIDIA TARNAWSKA</td> <td>02/24/2014</td> </tr> </tbody> </table>		Name	Execution Date	SARAD BAHADUR THAPA	02/24/2014	THOMAS SCHROEDER	02/24/2014	LIDIA TARNAWSKA	02/24/2014
Name	Execution Date								
SARAD BAHADUR THAPA	02/24/2014								
THOMAS SCHROEDER	02/24/2014								
LIDIA TARNAWSKA	02/24/2014								
RECEIVING PARTY DATA									
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Postal Code:	81737								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14197296</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14197296				
Property Type	Number								
Application Number:	14197296								
CORRESPONDENCE DATA									
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NAME OF SUBMITTER:	LIDIA FREISMUTH								
Signature:	/Lidia Freismuth/								

Date:	03/05/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 2 source=Declaration_and_Assignment#page1.tif source=Declaration_and_Assignment#page2.tif	

ASSIGNMENT AND DECLARATION (37 C.F.R. 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 C.F.R. 1.76)

Title of Invention **SEMICONDUCTOR WAFER WITH A LAYER OF Al₃Ga_{1-z}N AND PROCESS FOR PRODUCING IT**

As a below named inventor, I hereby declare that:

This declaration is directed to:

- The attached application, or
- United States application or PCT international application number 14/197,296 filed on March 5, 2014. (I hereby authorize the insertion of the application filing date and number when they become known.)

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. § 1.56.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I do hereby assign, sell and set over to SILTRONIC AG, a corporation organized and existing under the laws of the state or country of Germany, and having a place of business at Hann-Seidel-Platz 4, Munich, Germany 81737, hereinafter referred to as the ASSIGNEE, its successors, assigns or other legal representatives, my entire right, title and interest, domestic and foreign, in and to the inventions and discoveries in the above-identified application including the right of said ASSIGNEE, its successors, assigns or other legal representatives to make applications and to receive Letters Patent for said inventions and discoveries in any and all foreign countries in its or their own name or names, or in my name, at its or their election, and I hereby assign, sell and set over to said ASSIGNEE, its successors, assigns or other legal representatives, all rights of priority, including any provisional applications, in and to said inventions and discoveries in all countries, including all applications claiming benefit of the filing date hereof, continuations, continuations-in-part, divisionals, reexaminations and reissue applications.


And I hereby agree for myself, my heirs, successors, assigns or other legal representatives to execute any and all papers, including applications for Letters Patent of any and all kinds and in any and all countries and to perform any and all acts which said ASSIGNEE, its successors, assigns or other legal representatives may deem necessary to secure thereto the rights herein assigned, sold and set over.

And I hereby represent and warrant that I have not granted any rights inconsistent with the rights granted herein.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years or both.

LEGAL NAME OF INVENTOR

Inventor: Sarad Bahadur THAPA Date: 24.02.2014

Signature: 

Page 1 of 2 (Supplemental Sheet with Additional Joint Inventors is attached if necessary)

Note: An Application Data Sheet (PTO/SF/14 or equivalent), including naming the entire inventive entity, must accompany this form.

SUPPLEMENTAL SHEET FOR ASSIGNMENT AND DECLARATION (37 C.F.R. 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 C.F.R. 1.76) | **Additional Inventors Page 2 of 2**

Title of Invention | SEMICONDUCTOR WAFER WITH A LAYER OF AlzGa1-zN AND PROCESS FOR PRODUCING IT

Legal Name of Additional Joint Inventor:
Inventor: Thomas SCHROEDER | Date: 24th February 2014
Signature: *T. Schroeder*

Legal Name of Additional Joint Inventor:
Inventor: Lidia TARNAWSKA | Date: 24th February 2014
Signature: *Lidia Tarnawska*

Legal Name of Additional Joint Inventor:
Inventor: _____ | Date: _____
Signature: _____

Legal Name of Additional Joint Inventor:
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